



Solutions Across the Board

GAP PAD®



GAP PAD[®] provide an effective thermal interface between metal module housings and components where air gaps and rough surface textures are present.

GAP FILLER and LIQUI FORM



BERGQUIST® Gap Fillers are low stress, liquid materials ideal for providing thermal control for fragile, dimensionally complex components and electronic structures. Gap Fillers are available in two-part and onepart versions.

Phase Change Material



BERGQUIST phase change TIMs are solid at room temperature and, at elevated temperatures, change to liquid to fill gaps and deliver thermal control by providing excellent thermal impedance between components and the metal module housing.

SIL PAD®



SIL PAD[®] are an effective thermal interface between metal module housing and components, providing a robust dielectric interface to help meet safety agency requirements.

BOND PLY



BOND PLY thermal adhesives offer proven thermal and dielectric performance while eliminating the need for mechanical joinging mechanisms such as clips and screws.

TCLAD



TCLAD insulated metal substrates provide a wide range of constructions to meet thermal requirements for applications where conventional FR4 PCB substrates are not sufficient to manage the thermal load. TCLAD substrates are safety agency certified solutions and enable excellent heat transfer for surface mount power components.

Henkel AG & Co. KGaA Henkelstraße 67 40589 Düsseldorf | Germany Phone: +1 952 486 6313 E-mail: electronics@henkel.com www.henkel-adhesives.com/electronics



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Solutions Across the Board

Circuit Board Protection – Underfill



LOCTITE[®] brand underfills are low CTE materials designed to flow and encapsulate array interconects such as those within CSP, BGA and flip chip components. Underfill solder joint protection significantly enhances reliability performance and reworkable formulations enable preservation of high-value PCBs. Circuit Board Protection - Potting



Henkel potting materials are available in low outgassing formulations and a variety of viscosities and thermal performance capabilities, offering encapsulation and protection of a broad range of substrates. Circuit Board Protection -Conformal Coating



Henkel conformal coatings deliver rugged protection of circuit boards without limiting manufacturing throughput, protecting PCBs from moisture, corrosion and other harsh condiditons.

Circuit Board Protection – Encapsulant



High-purity, ionically-clean glob top and dam and fill encpsulants offer protection for a components of varying sizes and heights.

Solder



Henkel's LOCTITE solder pastes are best-in-class halogen-free, temperature-stable (GC series), ROHS-compliant formulations available in standard, waterwashable, lead-free and tin-lead solutions.

Peelable Mask



TECHNOMELT® peelable mask is an automated solution for replacement of costly, time-consuming manual masking operations. The material can be automatcially dispensed to protect sensitive components during the conformal coating process. Following conformal coating, the maks peels off cleanly, leaving no residue.

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Solutions Across the Board

Electrically Conductive Adhesives - Paste



Dispensable and screen printable pastes for the most demanding applications needing both excellent electrical and thermal performance.

Electrically Insulating Adhesives – Paste



Electrically insulating materials for chip attach applications that eliminate concerns of reliability and outgassing.

Electrically Conductive Adhesives – Film



High electrical and thermal performing adhesives in a film format cut exactly to meet your custom specifications.

Electrically Insulating Adhesives – Film



Electically insulating adhesives in a film format for high strength requirements due to difficult to bond to substrates or CTE mismatch.

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